

VERSION OF AMENDED CLAIMS TO SHOW CHANGES

MADE THERETO

2. (Amended) An electrical attachment comprising:
 - a module having [connection pads on] a bottom surface;
 - [a standoff, positioned on the bottom surface, having a height]
 - a printed circuit board [having connection pads];
 - a ball grid array, [interposing the connection pads of the module and the printed circuit board, wherein the height of the ball grid array is comparable to the height of the standoff] interposed between the bottom surface of the module and the printed circuit board;
 - a standoff, positioned on the bottom surface, having a height; wherein the standoff maintains the bottom surface of the module and the printed circuit board at the height of the standoff during reflow.

Before Reflow:

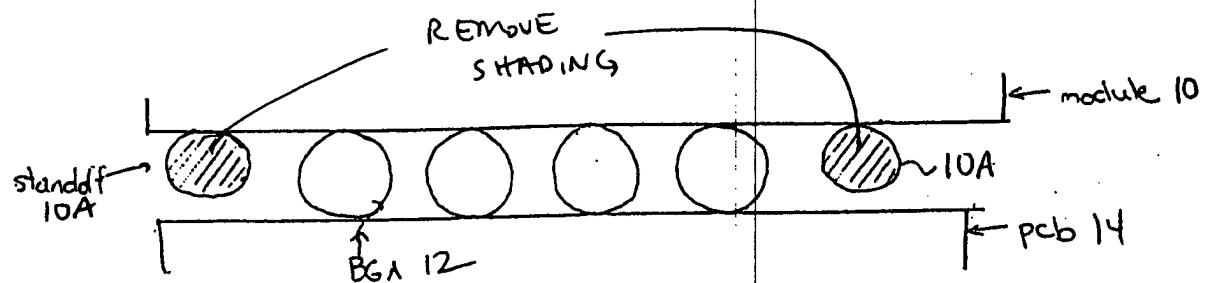


FIGURE 1A

Net
approx
6/10/02

After Reflow:

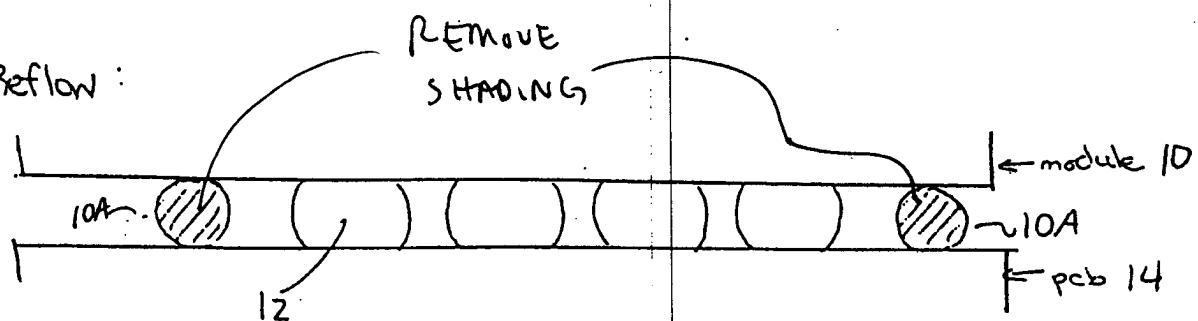


FIGURE 1B